

WHAT IS CLAIMED IS:

1. An exposure apparatus which exposes a substrate through a pattern of an original plate, comprising:
a part made of resin; and
means for controlling the temperature of the resin part at a predetermined temperature or lower.
2. An exposure apparatus according to Claim 1, further comprising a stage for moving the original plate,
the resin part being piping through which a fluid for cooling the stage for the original plate flows.
3. An exposure apparatus according to Claim 1, further comprising a stage for moving a substrate,
the resin part being piping through which a fluid for cooling the stage for the substrate flows.
4. An exposure apparatus according to Claim 1, wherein the predetermined temperature is lower than the temperature of the substrate.
5. An exposure apparatus according to Claim 1, further comprising a stage for moving the original plate; and
a chamber enclosing the stage for the original plate,

wherein the predetermined temperature is lower than the temperature of an inner-wall of the chamber.

6. An exposure apparatus according to Claim 1, further comprising a stage for moving a substrate; and a chamber enclosing the stage,

wherein the predetermined temperature is lower than the temperature of an inner-wall of the chamber.

7. An exposure apparatus according to Claim 1, wherein the predetermined temperature's maximum value is 18°C.

8. An exposure apparatus according to Claim 1, wherein the predetermined temperature is lower by at least 5°C than the temperature of the substrate.

9. An exposure apparatus according to Claim 1, wherein the resin part is piping, and the piping contains a first pipe through which a first fluid flows, and a second pipe through which a second fluid flows.

10. An exposure apparatus according to Claim 9, wherein the temperature of the first fluid is different than the temperature of the second fluid.

11. An exposure apparatus according to Claim 9,
wherein the piping is formed in such a manner that the
second pipe encloses the first pipe.

12. An exposure apparatus according to Claim 10,
wherein the temperature of the first fluid is lower than the
temperature of the second fluid.

13. An exposure apparatus according to Claim 9,
wherein the temperature of the second fluid is lower than
the predetermined temperature.

14. An exposure apparatus according to Claim 9,
wherein the temperature of the second fluid is lower than
the temperature of the substrate.

15. An exposure apparatus according to Claim 1,
wherein the resin part is piping, and the temperature-
control means has a mechanism for feeding into the piping
liquid or gas having a temperature controlled to a
predetermined value.

16. An exposure apparatus according to Claim 1,
wherein the resin part is piping, and the temperature-
control means has a cooling mechanism to cause a fluid

having a lower temperature than the temperature of the substrate to flow through the piping and a heating mechanism for heating at least a part of the cooling mechanism.

17. An exposure apparatus according to Claim 16, wherein the heating mechanism contains a Peltier device.

18. An exposure apparatus according to Claim 5, wherein the inside of the chamber is kept in a vacuum state.

19. An exposure apparatus according to Claim 6, wherein the inside of the chamber is kept in a vacuum state.

20. A method of producing a device fabricating method comprising the steps of:

exposing a substrate by means of using an exposure apparatus according to Claim 1; and
developing the exposed substrate.